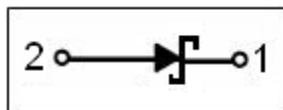


**/ Descriptions****/ Features****/ Applications****/ Equivalent Circuit****/ Pinning****/  $h_{FE}$  Classifications & Marking**

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/ Absolute Maximum Ratings(Ta=25 )

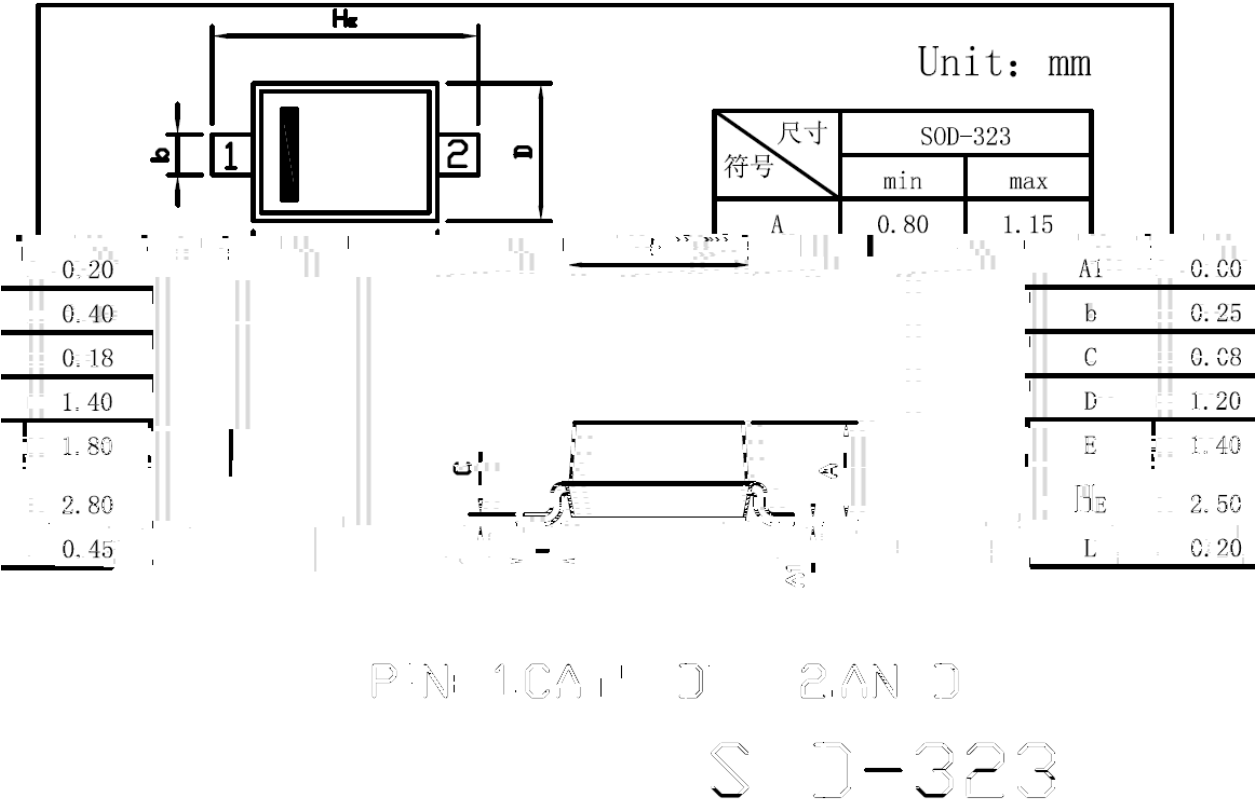
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/ Electrical Characteristics(Ta=25 )

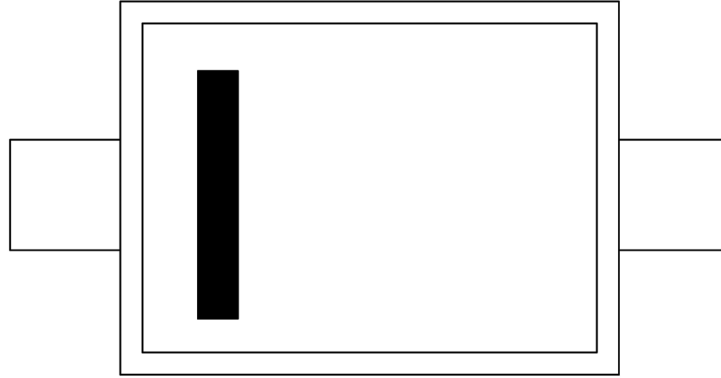
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/ Package Dimensions



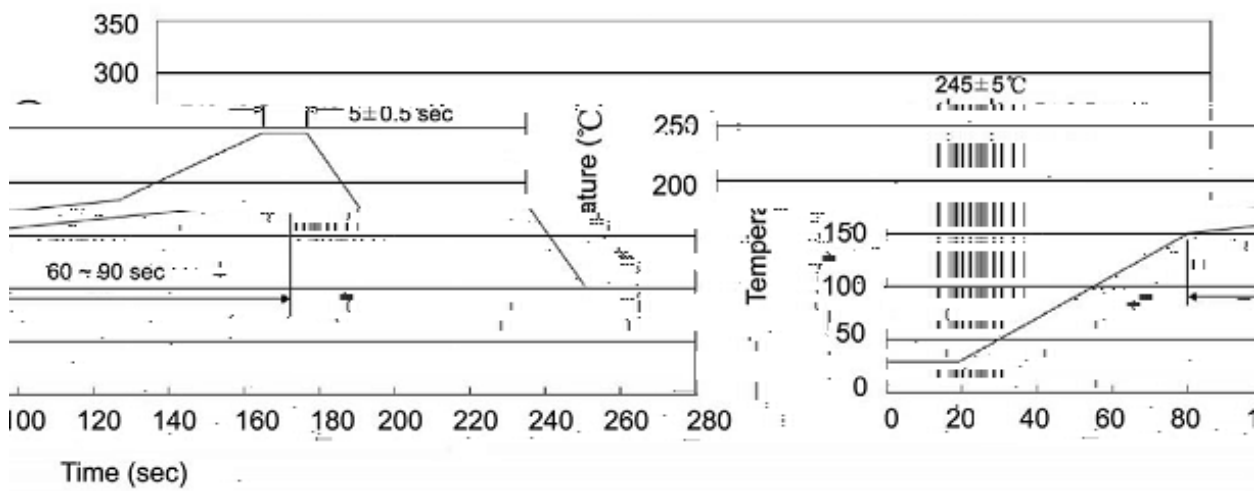
/ Marking Instructions



H

86

(     ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ± ± ±

/ Packaging SPEC.

| 封装形式 | 包装数量 |      |     |     |     | 包装尺寸 |   |   |
|------|------|------|-----|-----|-----|------|---|---|
|      | 只 卷盘 | 卷盘 盒 | 只 盒 | 盒 箱 | 只 箱 |      | 盒 | 箱 |
|      |      |      |     |     |     |      |   |   |

/ Notices